JAPANESE
INDUSTRIAL
STANDARD

Translated and Published by
Japanese Standards Association

JIS Z 3284-3 : 2024

(JWES/JSA)

Solder paste — Part 3: Test methods for printability, viscosity, slump and tackiness

ICS 25.160.50; 31.180
Reference number: JIS Z 3284-3 : 2024 (E)

Date of Establishment: 2014-06-20

Date of Revision: 2024-01-22

Date of Public Notice in Official Gazette: 2024-01-22

Investigated by: Japanese Industrial Standards Committee

Standards Board for ISO area

JIS Z 3284-3 : 2024, First English edition published in 2025-05

Translated and published by: Japanese Standards Association
Mita Avanti, 3-11-28, Mita, Minato-ku, Tokyo, 108-0073 JAPAN

In the event of any doubts arising as to the contents,
the original JIS is to be the final authority.

Printed in Japan HN

Contents

Page

Foreword

This Japanese Industrial Standard has been revised by the Minister of Economy, Trade and Industry through deliberations at the Japanese Industrial Standards Committee as the result of proposal for revision of Japanese Industrial Standard submitted by The Japan Welding Engineering Society (JWES)/Japanese Standards Association (JSA) with a draft being attached, based on the provision of Article 12, paragraph (1) of the Industrial Standardization Act applied mutatis mutandis pursuant to the provision of Article 16 of the said Act. This edition replaces the previous edition (**JIS Z 3284-3** : 2014), which has been technically revised.

Attention is drawn to the possibility that some parts of this Standard may conflict with patent rights, published patent application or utility model rights. The relevant Minister and the Japanese Industrial Standards Committee are not responsible for identifying any of such patent rights, published patent application or utility model rights.

JIS Z 3284 series consists of the following 4 parts under the general title Solder paste:

Part 1: Kinds and quality classification

Part 2: Test methods for solder particle shape, surface condition judgment, and particle size distribution

Part 3: Test methods for printability, viscosity, slump and tackiness

Part 4: Test methods for wettability, solderball and spread

Solder paste — Part 3: Test methods for printability, viscosity, slump and tackiness

Introduction

This Japanese Industrial Standard has been prepared based on IEC 61189-5-3 : 2015, Edition 1, with some modifications of the technical contents to reflect the current situation in Japan.

The vertical lines on both sides and dotted underlines indicate changes from the corresponding International Standard. A list of modifications with the explanations is given in Annex JB. Annex JA is unique to JIS and not given in the corresponding International Standard.

1 Scope

This Standard specifies the printability test, viscosity characteristic test, slump-in-printing test, slump-in-heating test and tackiness test of the solder paste for soldering used for the wiring connection, connection of parts, etc. of electric equipment, electronic equipment, communication equipment, etc.

NOTE The International Standard corresponding to this Standard and the symbol of degree of correspondence are as follows.

IEC 61189-5-3 : 2015 *Test methods for electrical materials, printed boards and other interconnection structures and assemblies — Part 5-3: General test methods for materials and assemblies — Soldering paste for printed board assemblies* (MOD)

In addition, symbols which denote the degree of correspondence in the contents between the relevant International Standard and JIS are IDT (identical), MOD (modified), and NEQ (not equivalent) according to ISO/IEC Guide 21-1.

2 Normative references

Part or all of the provisions of the following standards, through reference in this text, constitute provisions of this Standard. The most recent editions of the standards (including amendments) indicated below shall be applied.

JIS C 5603 *Terms and definitions for printed circuits*

JIS K 5500 *Glossary of terms for coating materials*

JIS K 8839 *2-Propanol (Reagent)*

JIS R 6252 *Abrasive papers*

JIS Z 3001-1 *Welding and allied processes — Vocabulary — Part 1: General*

JIS Z 3001-3 *Welding and allied processes — Vocabulary — Part 3: Soldering and*